

Datasheet revision 1.1

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Heat Sink Compound – Grey Ultra Conductive 10g Syringe 5cc

Product Highlights

- Lead-Free / RoHS 3 Compliant / REACH • Compliant
- Ultra High-Density Thermal Paste, Grev, noncuring, flowable, thermally conductive heat sink compound. Heavily filled with heat-conductive metal oxide. Provides extremely high thermal conductivity, low bleed and high temperature stability.
- Electrically insulating (7 x 10¹² ohm-cm)



Viscosity:	95,000 cP (95,000 mPa⋅s)
Density:	2.5g/cc
Thermal Conductivity:	4.3 W/m·K
Thermal Resistance:	0.06 °C*cm²/W
Electrical Volume Resistivity:	7 x 10 ¹² ohm-cm
Size:	10g Syringe (5cc)

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Shelf Life >24 months

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Chip Quik® Thermal Paste Orderable Part Numbers

Thermal Conductivity (W/m⋅K)	Thermal Resistance (°C*cm^2/W)	Density (g/cc)	Color	Package	Size (g)	Orderable Part Number
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G